



Docket No.: M4065.0127/P127-A
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Kie Y. Ahn et al

Allowed: May 19, 2004

Application No.: 09/660,324

Art Unit:2823

Filed: September 12, 2000

Examiner: F. Toledo

For: METHOD OF MAKING A CHIP
PACKAGING DEVICE HAVING AN
INTERPOSER

AMENDMENT UNDER 37 C.F.R. § 1.312

Dear Sir
U.S. Patent and Trademark Office
220 20th Street S.
Customer Window, Mail Stop Issue Fee
Crystal Plaza Two, Lobby, Room 1 B03
Arlington, VA 22202
(10/25/04)

Dear Sir:

In accordance with the provisions of 37 C.F.R. § 1.312, Applicant respectfully
requests entry of the following amendments.

Amendments to the Specification begin on page 2 of this paper.

Remarks begin on page 3 of this paper.